NCE N-Channel Enhancement Mode Power MOSFET

DESCRIPTION

The NCE1505S uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

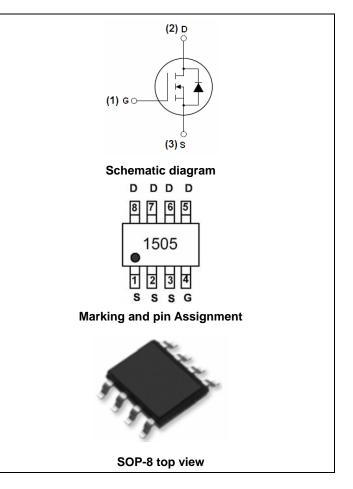
GENERAL FEATURES

- $V_{DS} = 150V, I_D = 5.2A$ $R_{DS(ON)} < 44m\Omega @ V_{GS} = 10V$ (Typ: $31m\Omega$)
- High density cell design for ultra low Rdson
- Fully characterized Avalanche voltage and current
- Low Gate to Drain Charge to Reduce Switching Losses

Application

- Power switching application
- Hard Switched and High Frequency Circuits
- Uninterruptible Power Supply

100% ΔVds TESTED!



Package Marking And Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
1505	NCE1505S	SOP-8	Ø330mm	12mm	2500 units

Absolute Maximum Ratings (TA=25℃unless otherwise noted)

Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	150	V	
Gate-Source Voltage	V _{GS}	±20	V	
Drain Current-Continuous	I _D	5.2	Α	
Drain Current-Continuous(T _C =100 °C)	I _D (100℃)	3.7	Α	
Pulsed Drain Current(Note 1)	I _{DM}	42	Α	
Maximum Power Dissipation	P _D	3.5	W	
Operating Junction and Storage Temperature Range	T_{J} , T_{STG}	-55 To 150	$^{\circ}$	

Thermal Characteristic

Thermal Resistance, Junction-to-Case(Note 2)	$R_{ heta JC}$	35.7	°C/W
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Electrical Characteristics (TA=25℃ unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit

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NCE1505S

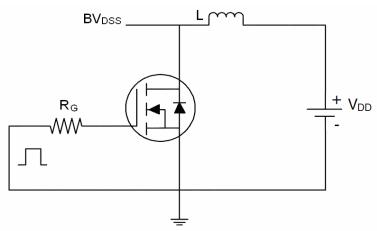
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	150	170	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =150V,V _{GS} =0V	-	-	1	μΑ
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	$V_{GS(th)}$	V _{DS} =V _{GS} ,I _D =250μA	2.5	3.2	4.5	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =5.2A	-	31	44	mΩ
Forward Transconductance	g FS	V _{DS} =50V,I _D =5.2A	12	-	-	S
Dynamic Characteristics (Note4)	-		•	•		
Input Capacitance	C _{lss}	\\ O5\\\\ O\\	-	1700	-	PF
Output Capacitance	Coss	- V _{DS} =25V,V _{GS} =0V, F=1.0MHz	-	190	-	PF
Reverse Transfer Capacitance	C _{rss}	F=1.UMHZ	-	90	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t _{d(on)}		-	15	-	nS
Turn-on Rise Time	t _r	V _{DD} =75V,I _D =3.1A	-	13	-	nS
Turn-Off Delay Time	t _{d(off)}	V_{GS} =10V, R_{GEN} =6.5 Ω	-	26	-	nS
Turn-Off Fall Time	t _f		-	14	-	nS
Total Gate Charge	Q_g	\/ -75\/ -2.44	-	35.8	-	nC
Gate-Source Charge	Q_{gs}	$V_{DS}=75V,I_{D}=3.1A,$ $V_{GS}=10V$	-	7.5	-	nC
Gate-Drain Charge	Q_{gd}	V _{GS} -10V	-	13	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V_{SD}	V _{GS} =0V,I _S =3.1A	-	-	1.2	V
Diode Forward Current (Note 2)	Is		-	-	2.7	Α
Reverse Recovery Time	trr	$T_J = 25^{\circ}\text{C}, I_F = 3.1\text{A},$	-	50	-	nS
Reverse Recovery Charge	Qrr	V _{DD} = 25V,di/dt = 100A/μs	-	140	-	nC

Notes:

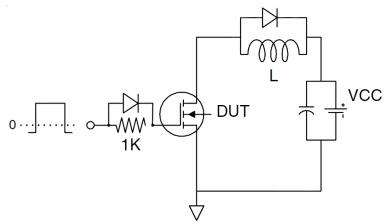
- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- **2.** Surface Mounted on FR4 Board, $t \le 10$ sec.
- 3. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production

Test circuit

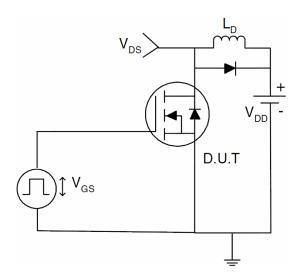
1) E_{AS} test Circuits



2) Gate charge test Circuit:



3) Switch Time Test Circuit:



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (Curves)

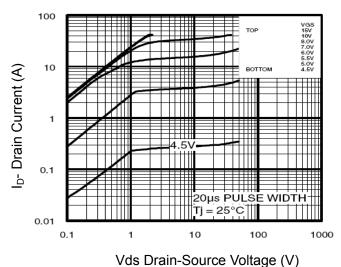


Figure 1 Output Characteristics

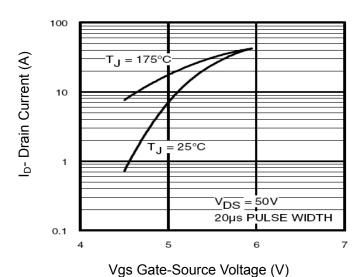


Figure 2 Transfer Characteristics

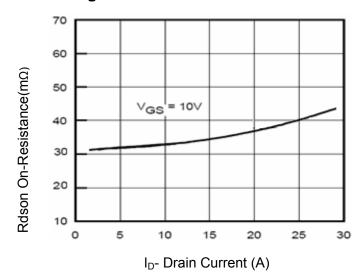


Figure 3 Rdson- Drain Current

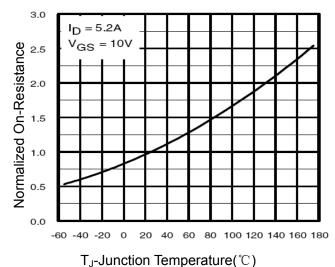


Figure 4 Rdson-JunctionTemperature

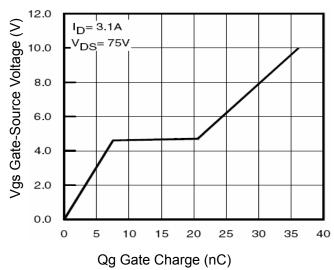


Figure 5 Gate Charge

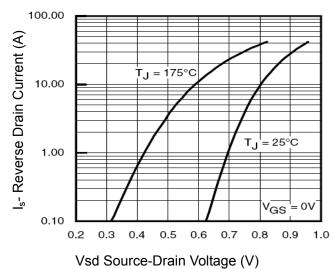


Figure 6 Source- Drain Diode Forward

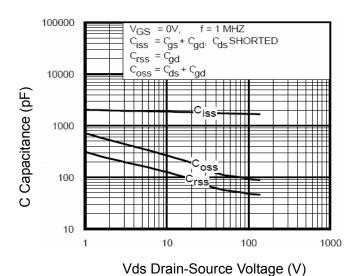


Figure 7 Capacitance vs Vds

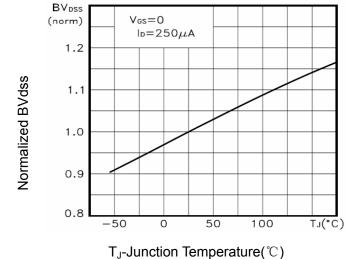


Figure 9 BV_{DSS} vs Junction Temperature

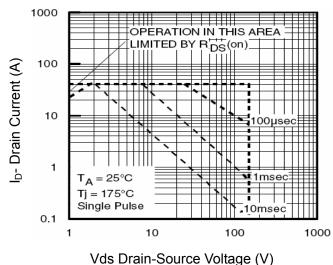
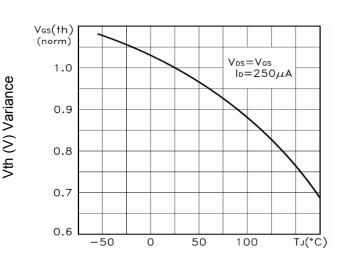


Figure 8 Safe Operation Area



 $\label{eq:TJ-Junction Temperature} T_{J}\mbox{-Junction Temperature}(^{\circ}\mbox{C})$ Figure 10 $\mbox{V}_{GS(th)}$ vs Junction Temperatur

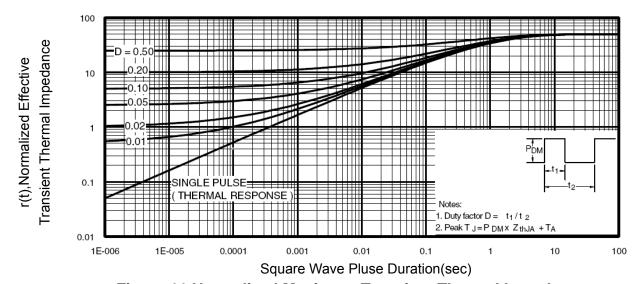
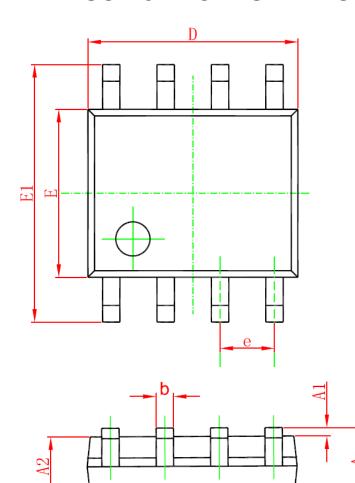
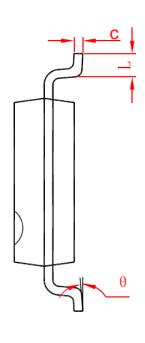


Figure 11 Normalized Maximum Transient Thermal Impedance

SOP-8 PACKAGE IN FORMATION





Comb a l	Dimensions Ir	n Millimeters	Dimensions In Inches		
Symbol	Min	Max	Min	Max	
A	1. 350	1. 750	0. 053	0. 069	
A1	0. 100	0. 250	0.004	0. 010	
A2	1. 350	1. 550	0. 053	0. 061	
b	0. 330	0. 510	0. 013	0. 020	
С	0. 170	0. 250	0.006	0. 010	
D	4. 700	5. 100	0. 185	0. 200	
Е	3. 800	4. 000	0. 150	0. 157	
E1	5. 800	6. 200	0. 228	0. 244	
е	1. 270	(BSC)	0.050	(BSC)	
L	0. 400	1. 270	0. 016	0. 050	
θ	0°	8°	0°	8°	

NCE1505S

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